

General Description

The Sanrise SRC65R230BS is a high voltage power MOSFET, fabricated using advanced super junction technology. The resulting device has extremely low on resistance, low gate charge and fast switching time, making it especially suitable for applications which require superior power density and outstanding efficiency.

The SRC65R230BS break down voltage is 650V and it has a high rugged avalanche characteristics. The SRC65R230BS is available in PDFN8*8-4 package.

Features

- Ultra Low $R_{DS(ON)} = 230m\Omega @ V_{GS} = 10V$.
- Ultra Low Gate Charge, $Q_g = 38.4nC$ typ.
- Intrinsic Fast-Recovery Body Diode
- Fast switching capability
- Robust design with better EAS performance
- Non-automotive Qualified
- Ultra-fast body diode

Application

- UPS, Inverter, etc
- Solar
- High Power AC/DC Power Supply

Symbol

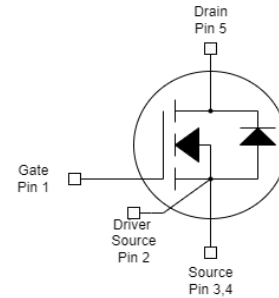
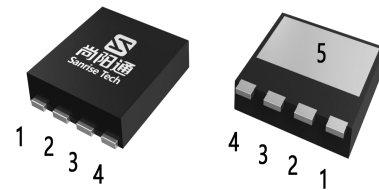


Figure 1 Symbol of SRC65R230BS

Package Type



PDFN8*8-4

Figure 2 Package Type of SRC65R230BS

Ordering Information

SRC65R230BS□□-□		
Circuit Type		E: Lead Free
		G: Green
Package		TR: Tape & Reel
D88: PDFN8*8-4		TY: Tray-3

Package	Part Number	Marking ID	Packing Type
PDFN8*8-4	SRC65R230BSD88TR-G	SRC65R230BSD88G	Tape & Reel

Absolute Maximum Ratings^{Note 1}

Parameter		Symbol	Rating	Unit
Drain-Source Voltage		V_{DSS}	650	V
Gate-Source Voltage		V_{GSS}	±30	V
Gate-Source Voltage (dynamic), AC ($f > 1$ Hz)		V_{GSS}	±30	V
Power Dissipation ($T_c = 25^\circ\text{C}$, PDFN8*8-4)		P_{tot}	178	W
Continuous Drain Current	$T_c = 25^\circ\text{C}$	I_D	21.2	A
	$T_c = 100^\circ\text{C}$		13.4	
	$T_c = 125^\circ\text{C}$		9.5	
Pulsed Drain Current (Note 2)		I_{DM}	64	A
Avalanche Energy, Single Pulse (Note 3)		E_{AS}	200	mJ
Avalanche Energy, Repetitive (Note 2)		E_{AR}	0.7	mJ
Avalanche Current, Repetitive (Note 2)		I_{AR}	2.5	A
Continuous Diode Forward Current		I_S	21.2	A
Diode Pulse Current		$I_{S,PULSE}$	64	A
Operating Junction Temperature		T_J	150	$^\circ\text{C}$
Storage Temperature		T_{STG}	-55 to 150	$^\circ\text{C}$
Lead Temperature (Soldering, 10 sec)		T_{LEAD}	260	$^\circ\text{C}$

Note:

1. Absolute maximum ratings are those values beyond which the device could be permanently damaged. Absolute maximum ratings are stress ratings only and functional device operation is not implied.
2. Repetitive Rating: Pulse width limited by maximum junction temperature
3. $I_{AS} = 2.5\text{A}$, $V_{DD} = 60\text{V}$, $R_G = 25\Omega$, Starting $T_J = 25^\circ\text{C}$

Thermal characteristics

Parameter		Symbol	Min	Typ	Max	Unit
Thermal resistance, Junction-to-Case	PDFN8*8-4	R_{thJC}			0.7	$^\circ\text{C} / \text{W}$
Thermal resistance, Junction-to-Ambient	PDFN8*8-4	R_{thJA}			62	$^\circ\text{C} / \text{W}$

Electrical Characteristics

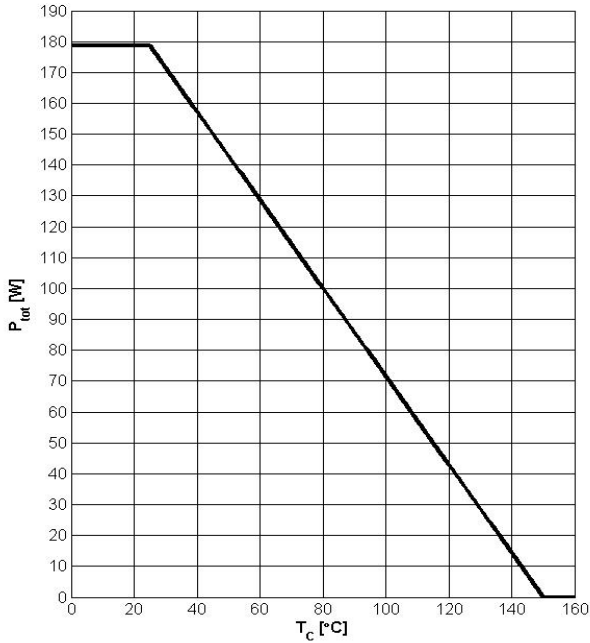
$T_J = 25\text{ }^{\circ}\text{C}$, unless otherwise specified.

Parameter		Symbol	Test Conditions	Min	Typ	Max	Unit
Statistic Characteristics							
Drain-Source Breakdown Voltage		BV _{DSS}	V _{GS} =0V, I _D =250uA	650			V
Zero Gate Voltage Drain Current		I _{DSS}	V _{DS} =650V, V _{GS} =0V			10	uA
Gate-Body Leakage Current	Forward	I _{GSSF}	V _{GS} =30V, V _{DS} =0V			100	nA
	Reverse	I _{GSSR}	V _{GS} =-30V, V _{DS} =0V			-1.0	uA
Gate Threshold Voltage		V _{GS(TH)}	V _{DS} =V _{GS} , I _D =250uA	2.3	3.3	4.3	V
Static Drain-Source On-Resistance		R _{DS(ON)}	V _{GS} =10V, I _D =10.0A		187	230	mΩ
Gate Resistance		R _G	f=1MHz, Open Drain		1.7		Ω
Dynamic Characteristics							
Input Capacitance		C _{ISS}	V _{DS} =25V, V _{GS} =0V, f=1MHz		1660		pF
Output Capacitance		C _{OSS}			1820		
Reverse Transfer Capacitance		C _{RSS}			23		
Effective output capacitance, energy related ^{NOTE5}		C _{O(er)}	V _{GS} =0V, V _{DS} =0...480V		71		pF
Effective output capacitance, time related ^{NOTE6}		C _{O(tr)}			301		
Turn-on Delay Time		t _{d(on)}	V _{DD} =400V, I _D =10.0A R _G =3.4Ω, V _{GS} =10V		11		ns
Rise Time		t _r			10		
Turn-off Delay Time		t _{d(off)}			76		
Fall Time		t _f			8		
Gate Charge Characteristics							
Gate to Source Charge		Q _{gs}	V _{DD} =480V, I _D =10.0A V _{GS} =0 to 10V		10.8		nC
Gate to Drain Charge		Q _{gd}			12.3		
Gate Charge Total		Q _g			38.4		
Gate Plateau Voltage		V _{plateau}			5.4		V
Reverse Diode Characteristics							
Drain-Source Diode Forward Voltage		V _{SD}	V _{GS} =0V, I _{SD} =10.0A		0.87	1.1	V
Reverse Recovery Time		t _{rr}	V _R =400V, I _F =10.0A dI _F /dt=100.0A/us		125		ns
Reverse Recovery Charge		Q _{rr}			0.78		uC
Peak Reverse Recovery Current		I _{rrm}			11.4		A

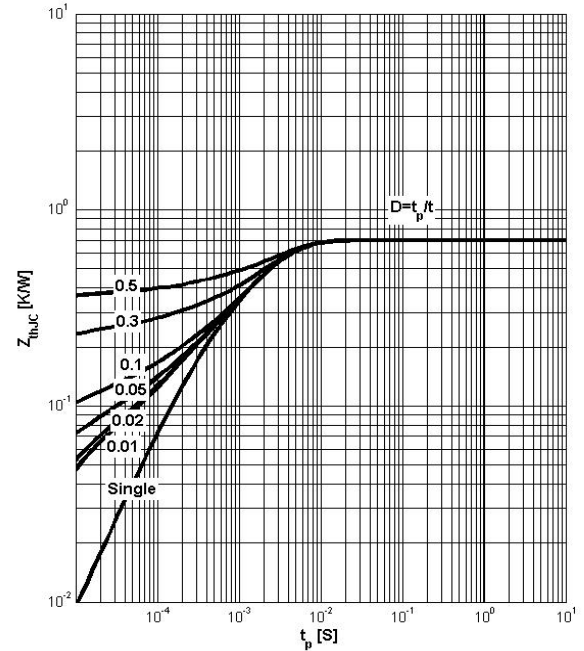
Note:

5. $C_{O(er)}$ is a fixed capacitance that gives the same stored energy as C_{OSS} while V_{DS} is rising from 0 to 480V

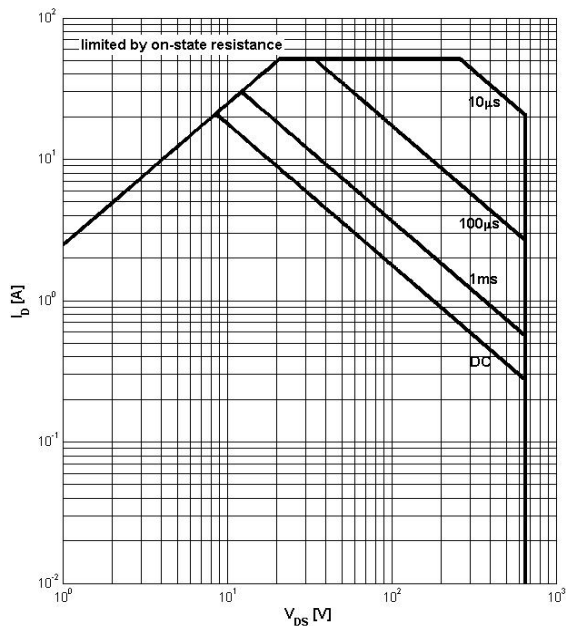
6. $C_{O(tr)}$ is a fixed capacitance that gives the same charging time as C_{OSS} while V_{DS} is rising from 0 to 480 V

Typical Performance Characteristics
Figure 3: Power Dissipation


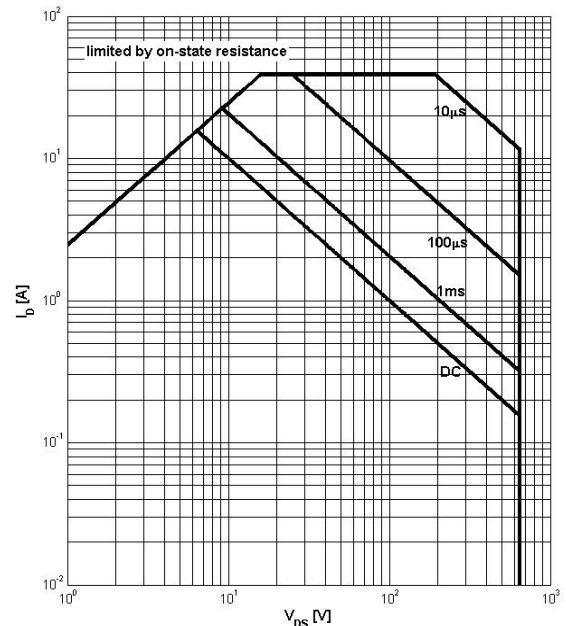
$$P_{tot} = f(T_c)$$

Figure 4: Max. Transient Thermal Impedance


$$Z_{thJC} = f(t_p); \text{ parameter: } D = t_p / T$$

Figure 5: Safe Operating Area


$$I_D = f(V_{DS}); T_c = 25^\circ\text{C}; V_{GS} > 7\text{V}; \text{ parameter } t_p$$

Figure 6: Safe Operating Area


$$I_D = f(V_{DS}); T_c = 80^\circ\text{C}; V_{GS} > 7\text{V}; \text{ parameter } t_p$$

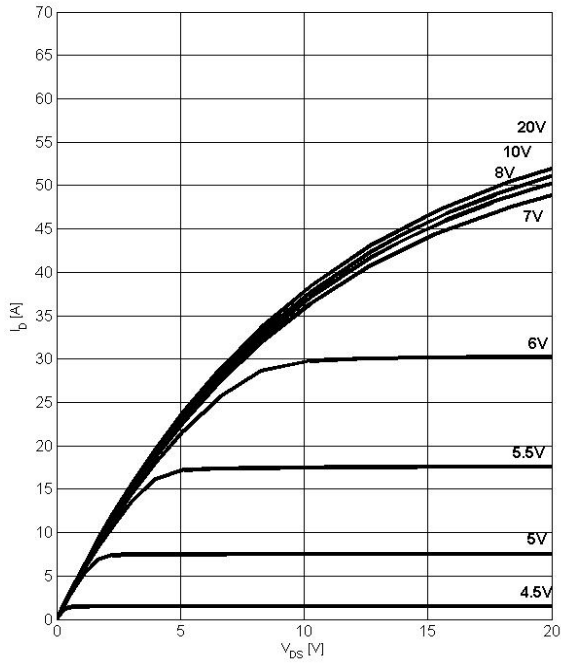
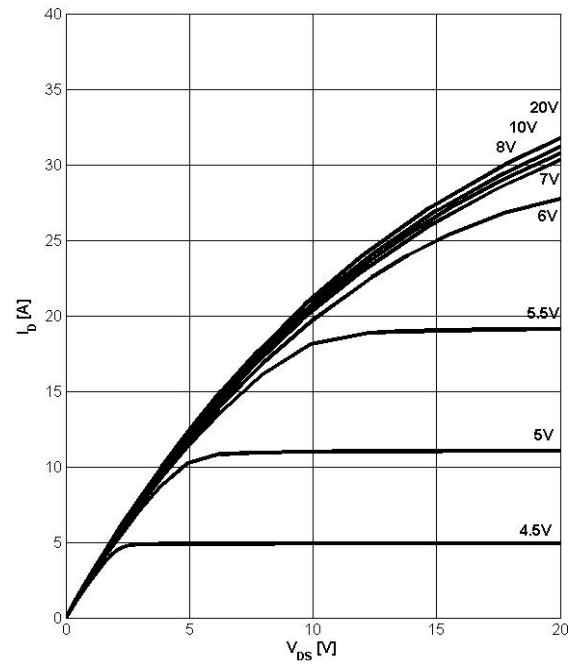
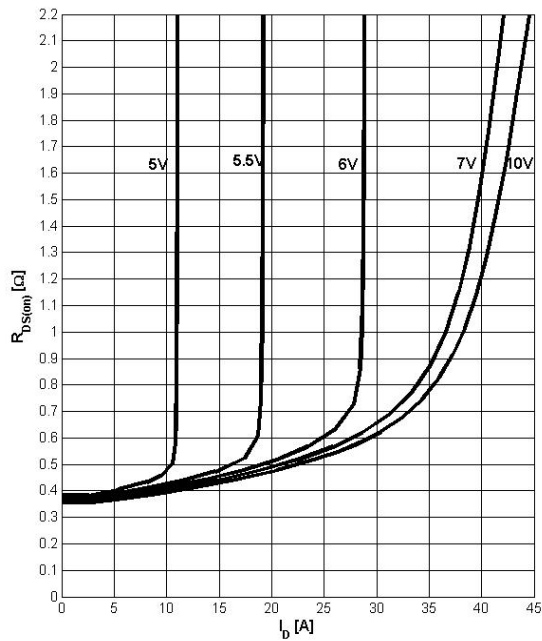
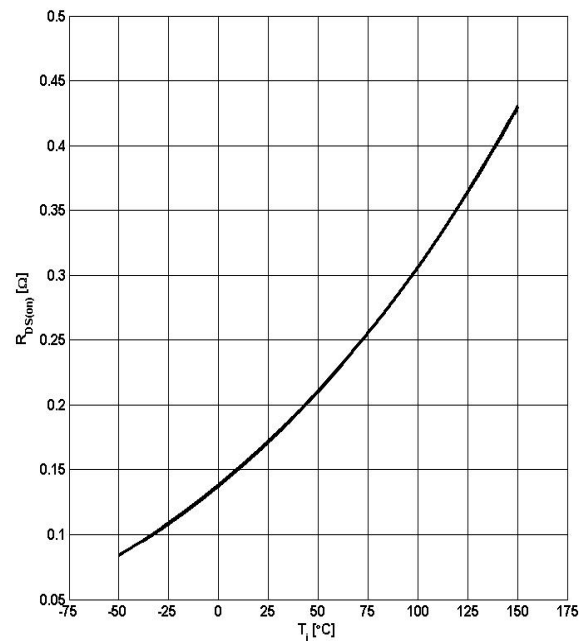
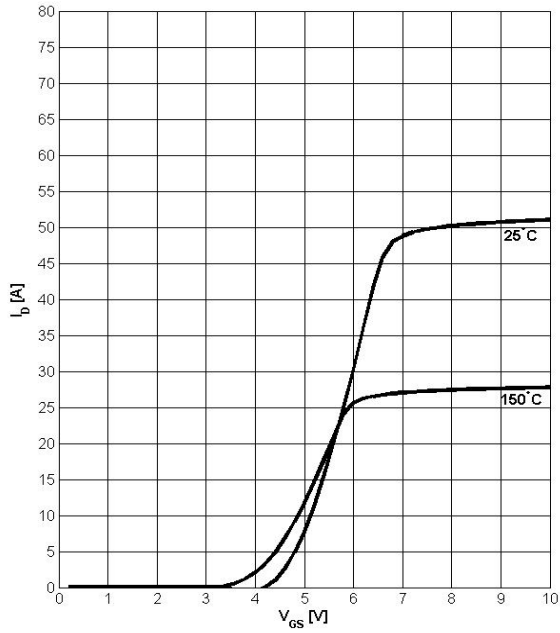
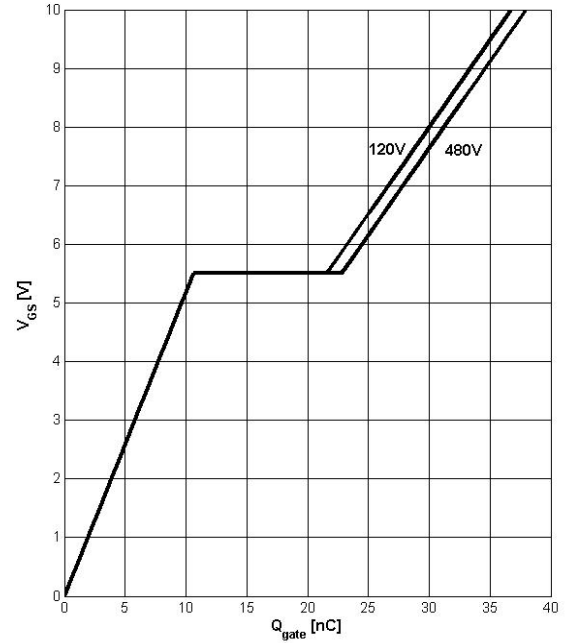
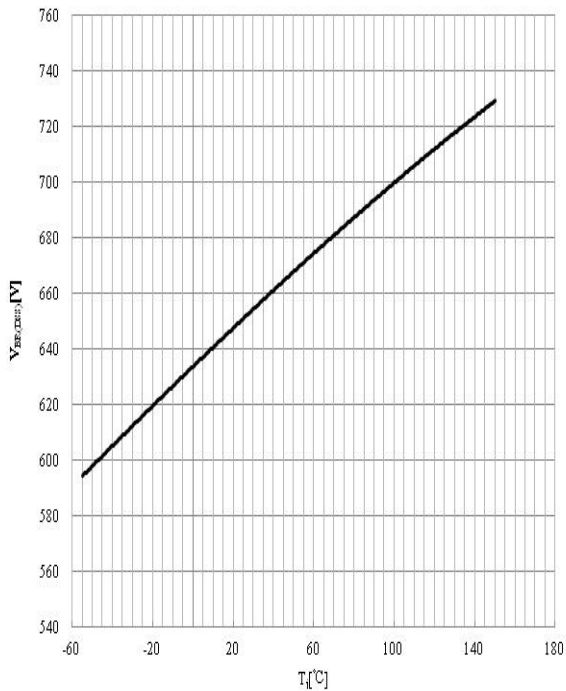
Figure 7: Typ. Output Characteristics

 $I_D = f(V_{DS}); T_j = 25^\circ\text{C}; \text{parameter: } V_{GS}$
Figure 8: Typ. Output Characteristics

 $I_D = f(V_{DS}); T_j = 125^\circ\text{C}; \text{parameter: } V_{GS}$
Figure 9: Typ. Drain-Source On-State Resistance

 $R_{DS(ON)} = f(I_D); T_j = 125^\circ\text{C}; \text{parameter: } V_{GS}$
Figure 10: Typ. Drain-Source On-State Resistance

 $R_{DS(ON)} = f(T_j); I_D = 10\text{A}; V_{GS} = 10\text{V}$

Figure 11: Typ. Transfer Characteristics


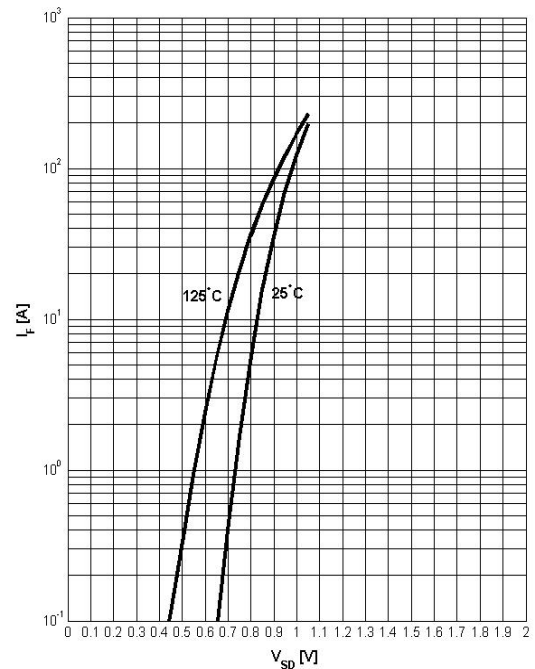
$$I_D = f(V_{GS}); V_{DS} = 20V$$

Figure 12: Typ. Gate Charge


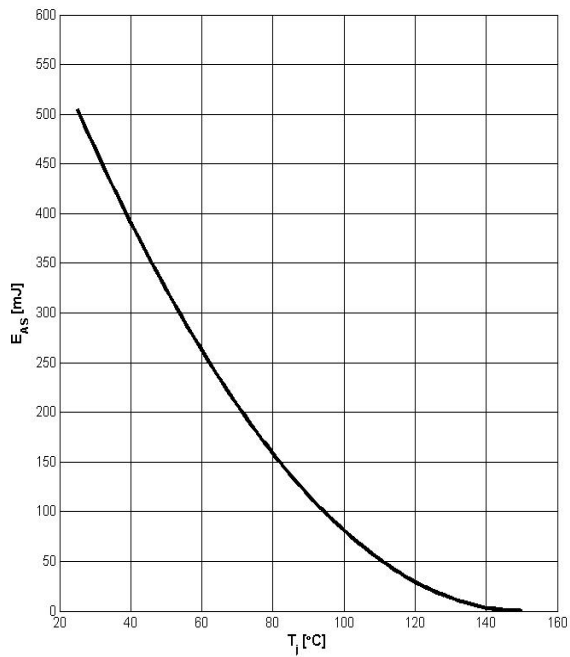
$$V_{GS} = f(Q_{gate}), I_D = 10A \text{ pulsed}$$

Figure 13: Drain-Source Breakdown Voltage


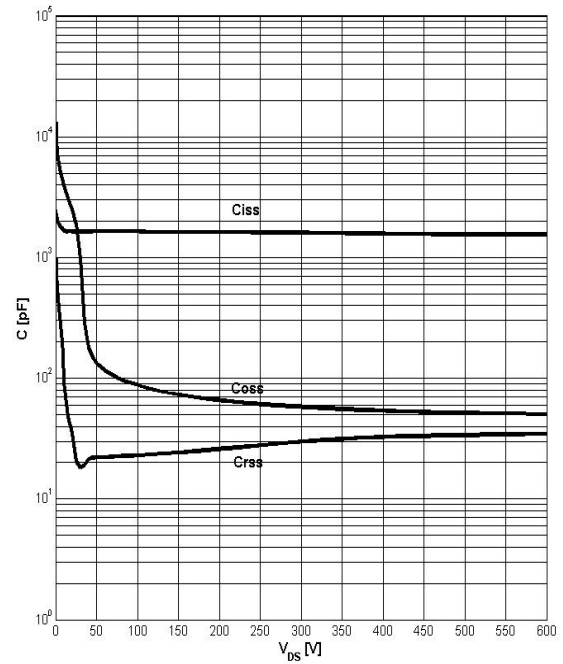
$$V_{BR(DSS)} = f(T_j); I_D = 10mA$$

Figure 14: Forward Characteristics of Reverse Diode


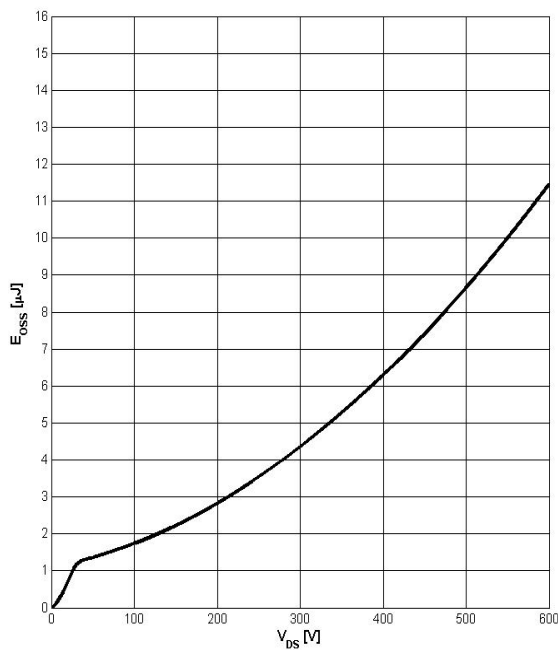
$$I_F = f(V_{SD}); \text{parameter: } T_j$$

230mΩ, 650V, Super Junction N-Channel Power MOSFET
SRC65R230BS
Figure 15: Avalanche Energy


$$E_{AS}=f(T_j); I_D=3.6A; V_{DD}=60V$$

Figure 16: Typ. Capacitances


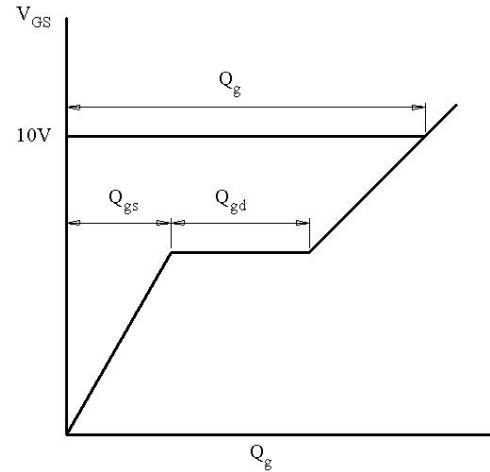
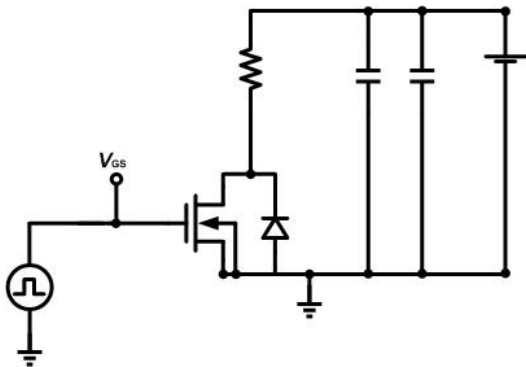
$$C=f(V_{DS}); V_{GS}=0; f=1MHz$$

Figure 17: Coss Stored Energy


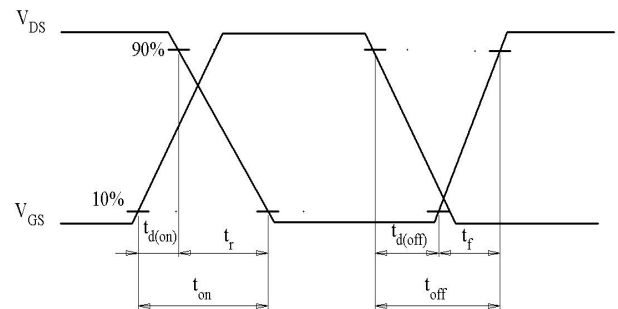
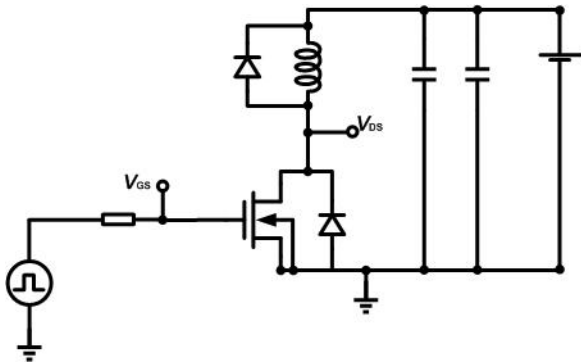
$$E_{OSS}=f(V_{DS})$$

Test Circuits

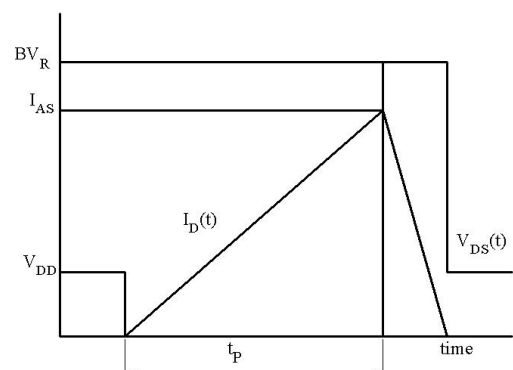
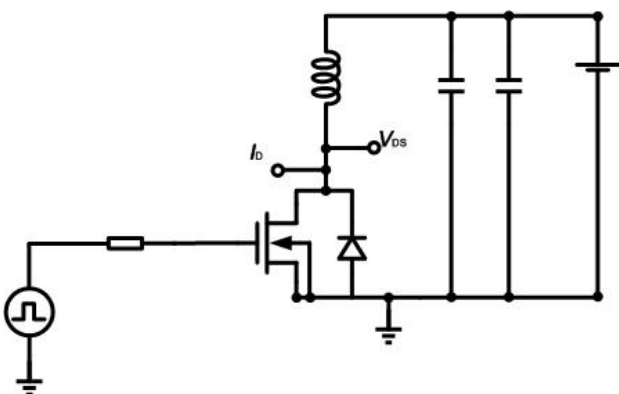
1. Gate Charge Test Circuit & Waveform

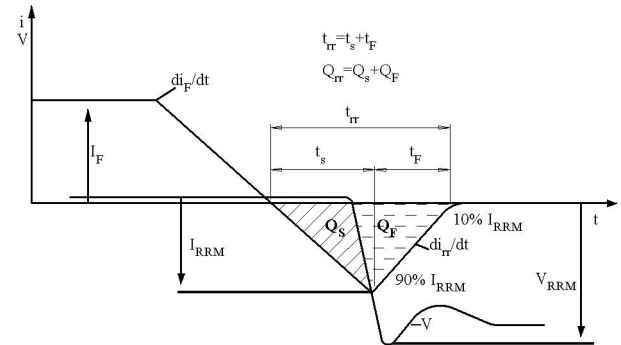
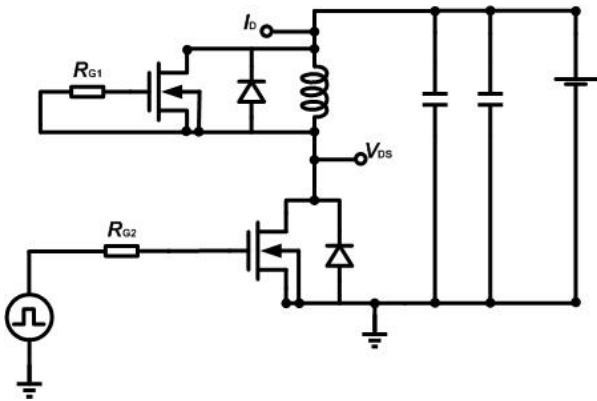


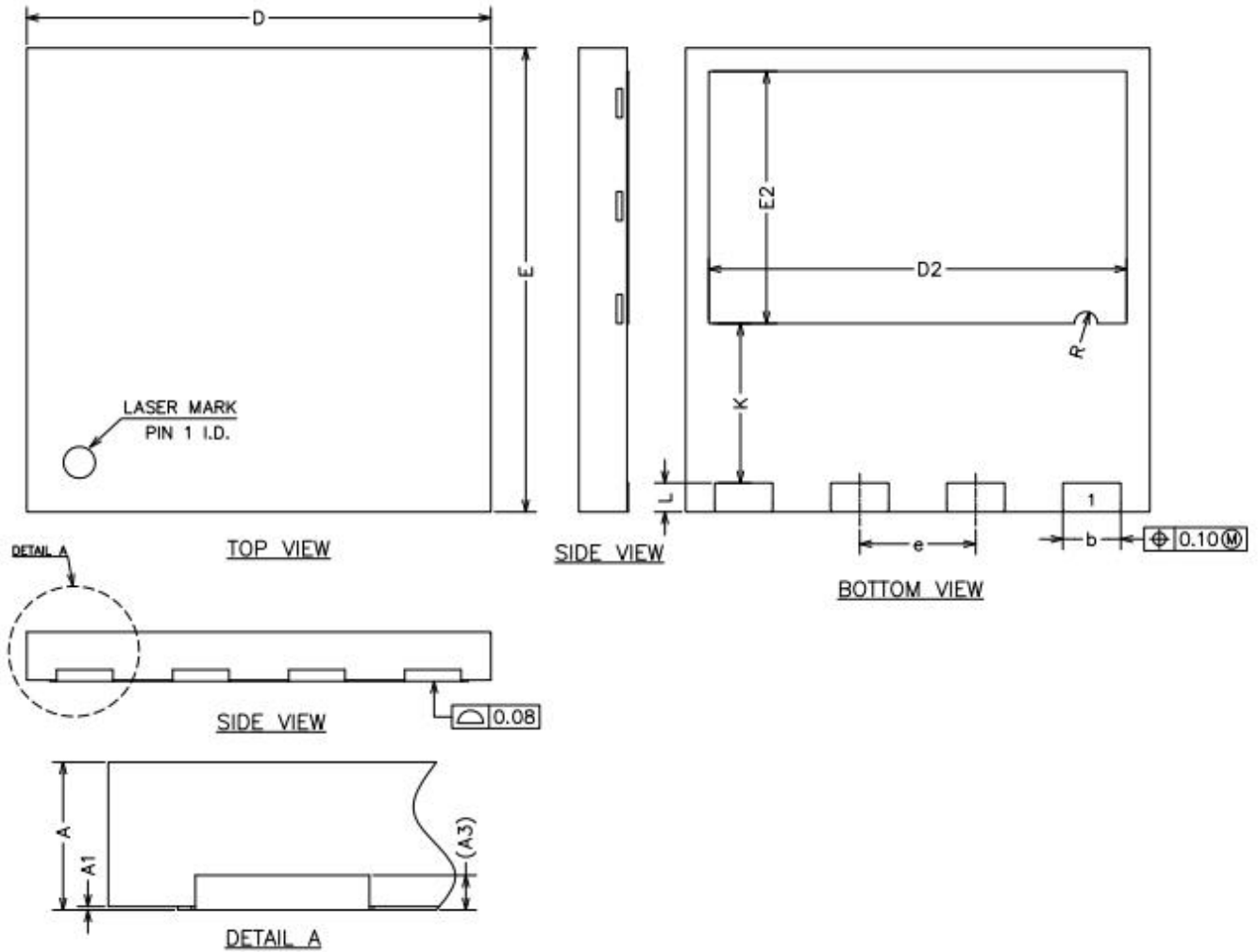
2. Switch Time Test Circuit



3. Unclaimed Inductive Switching Test Circuit & Waveforms



4. Test Circuit and Waveform for Diode Characteristics


Mechanical Dimensions
PDFN8*8-4
Unit: mm


Symbol	Dimensions(mm)			Symbol	Dimensions(mm)		
	Min.	Typ.	Max.		Min.	Typ.	Max.
A	0.80	0.85	0.90	D2	7.10	7.20	7.30
A1	0.00	0.02	0.05	E2	4.25	4.35	4.45
A3	-	0.20REF	-	e	1.90	2.00	2.10
b	0.90	1.00	1.10	K	2.65	2.75	2.85
D	7.90	8.00	8.10	L	0.40	0.50	0.60
E	7.90	8.00	8.10	R	-	0.20REF	-



Shenzhen Sanrise Technology Co., LTD

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Main Site:

- Headquarter

Shenzhen Sanrise Technology Co., LTD.
A1206, Skyworth building, No. 008, gaioxinnan 1st Road,
Gaoxin District, Yuehai street,, Nanshan District, ShenZhen,
P.R.China

Tel: +86-755-22953335

Fax: +86-755-22916878

- Shanghai Office

Shenzhen Sanrise Technology Co., LTD
Rm.401, Building B, No. 666, Zhangheng Road,
Zhangjiang Hi-Tech Park, Shanghai, P.R.China

Tel: +86-21-68825918